



2858

PATENT
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : D.Y.Shih, et al.
Serial Number : 09/254,769
Filing Date : March 11, 1999
Examiner : V. Nguyen
Group Art Unit : 2858
For :
WAFER SCALE HIGH DENSITY
PROBE ASSEMBLY,
APPARATUS FOR USE THEREOF
AND METHODS OF
FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Washington, D.C. 20231

On May 7, 2001, the Legal Instruments Examiner issued a Notice of Non-Compliant Amendment stating that the amendment submitted by Applicants on April 30, 2001 did not include a clean version of the amended claims.

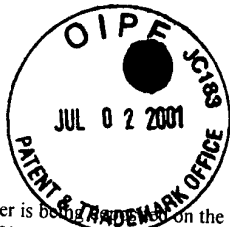
Applicants submit herewith the same amendment that was filed previously which does now and did then contain a clean version of the amended claims. Please review and approve the format of the enclosed amended claims. The Abstract is not included herein.

In view of the arguments and modifications to the claims, allowance of this case is warranted. Such favorable action is respectfully solicited.

Respectfully Submitted,

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I hereby certify that this paper is being mailed on the date indicated below with the
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